CloudDC SuperServer SYS-610C-TR



More details he

Key Applications

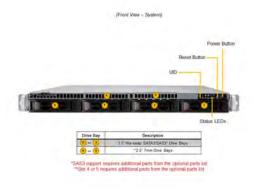
Web Server, Firewall Application, Data Center Optimized, Value IaaS, Cloud Computing, Compact Server, DNS & Gateway Servers, Firewall Application, CDN, Edge Nodes,

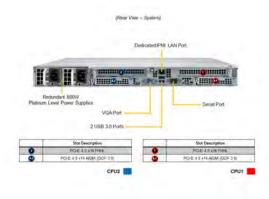
Key Features

- Dual sockets P+ (LGA-4189) 3rd Gen Intel® Xeon® Scalable processors;
- Intel® C621A Chipset;
- 16 DIMMs up to 6TB 3DS ECC DDR4-3200: LRDIMM/RDIMM/Intel® DCPMM;
- 2 PCle 4.0 x16 FHHL; 2 PCle 3.0 x2 NVMe M.2;
- Dual AIOM (OCP 3.0) slots with NCSI for networking, 1 dedicated IPMI LAN;
- 4x 3.5/2.5" hot-swap SATA/SAS drive bays;
- 6 counter-rotating 4 cm PWM fans with optimal fan speed control, 2 air shrouds:
- 860W redundant Platinum level 100-240Vac and 200-240 Vdc power supplies;
- 1 VGA, 1 COM, 2 USB 3.0 (rear);



Form Factor	1U Rackmount
	Enclosure: 437 x 43 x 650mm (17.2" x 1.7" x 25.6")
	Package: 602 x 196 x 866mm (23.7" x 7.7" x 34.1")
Processor	3rd Gen Intel® Xeon® Scalable processors
	Dual Socket LGA-4189 (Socket P4) supported
	TDP up to 270W; 3 UPI
	(CPUs with TDP higher than 185W may have support conditions due to power and thermal limitations.)
System Memory	16 DIMM slots
	Up to 4 TB ECC RDIMM, DDR4-3200MHz
	Up to 4 TB ECC LRDIMM, DDR4-3200MHz
	Up to 4 TB Intel® DCPMM, DDR4-3200MHz
Drive Bays	4x 3.5" hot-swap SATA/SAS drive bays (Default 3.5" drive trays can also support 2.5" drives.)
	2x PCle 3.0 x2
	M-Key, 2280
Expansion Slots	2 PCIe 4.0 x16 FHHL slot(s)
On-Board Devices	SATA: SATA3 (6Gbps); RAID 0/1/5/10 support
	Chipset: Intel® C621A
	Network Connectivity:
	with Advanced IO Module, AIOM (OCP 3.0 NIC, refer to AIOM Network Card(s) under Optional Parts List for options)
	IPMI: Support for Intelligent Platform Management Interface v.2.0
	IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
Input / Output	LAN: 1 Dedicated IPMI LAN port
	USB: 2 USB 3.0 port(s) (2 rear)
	Video: 1 VGA port(s)
	Serial Port: 1 COM Port(s) (1 rear)
	DOM: 1 SuperDOM (Disk on Module) port





System Cooling	6x 4cm heavy duty fan(s)
Power Supply	800W/860W 1U redundant power supply Dimension (W x H x L): 54.5 x 40.25 x 322 mm Output Type: Backplanes (gold finger)
System BIOS	BIOS Type: AMI 32MB SPI FLASH ROM
Management	SuperDoctor® 5; Watch Dog; NMI; SUM; KVM with dedicated LAN; SPM; Intel® Node Manager; SSM; IPMI 2.0; Redfish API; SCC
PC Health Monitoring	FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors CPU: Monitors for CPU Cores, Chipset Voltages, Memory. 8 Phase-switching voltage regulator
Dimensions and Weight	Height: 1.7" (43 mm) Width: 17.2" (437 mm) Depth: 25.6" (650 mm) Gross Weight: 28 lbs (12.7 kg) Packaging: 7.7" (H) x 23.7" (W) x 34.1" (D) Available Color: Black
Operating Environment	Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -40°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	Super X12DDW-A6
Chassis	CSE-LA15TQC-R860AW